# Bright Mid-Wave Infrared Resonant-Cavity Light-Emitting Diodes Based on Black Phosphorus

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enhances the emission efficiency, and a thin transparent conducing oxide [indium tin oxide (ITO)] layer, which reduces the parasitic resistance, both resulting in order of magnitude improvements to performance.

KEYWORDS: bP, LED, two-dimensional (2D) materials, parasitic resistance, light extraction efficiency, ITO

he mid-wave infrared spectral range (MWIR,  $\lambda = 3-8$  $\mu$ m), is classified as eye safe, which makes it attractive for applications including target imaging, illumination, and freespace optical communication. In addition, MWIR covers fundamental vibrational resonance bands of a wide range of materials, including water, polymers, toxic and explosive agents, and molecular gases, such as CO<sub>2</sub> and methane.<sup>1</sup> An application related to the latter, i.e., gas sensing, has been of much interest lately, e.g., for smart homes, oil and gas production, and wearable health monitoring. This growing market has motivated the development of III-V and II-VI semiconductor-based laser technologies, such as quantumcascade lasers (QCLs), interband cascade lasers (ICLs), and quantum-well lasers. These provide high optical power and narrow spectral width but with the trade-off of system complexity and high power requirement and fabrication cost.<sup>2</sup> Inexpensive alternatives, such as thermal light emitters, come at the cost of broad spectral width and limited modulation frequencies.<sup>2,3</sup> In contrast, light-emitting diodes (LEDs) present the opportunity for low cost but also have favorable characteristics, such as brightness adjustment via pulse-width modulation and narrow spectral width.

Conventional MWIR LEDs based on III–V and II–VI semiconductors exhibit low efficiencies (even theoretically) as a result of a high Auger recombination coefficient, which is inherent to semiconductors with small bandgap and large asymmetry in carrier effective masses.<sup>4</sup> Therefore, there is a

tremendous technological need for the development of a new emitter material in the MWIR with higher quantum yield and efficiency. Black phosphorus (bP), a two- dimensional (2D) material, has a much lower Auger recombination coefficient compared to III–V and II–VI semiconductors with similar bandgaps as a result of smaller asymmetry in effective masses, presenting an opportunity as the emitting layer for more efficient MWIR LEDs.<sup>5–7</sup> A lower Auger recombination coefficient leads to a higher quantum yield (QY), which is the fraction of recombination events that emit photons and is given by the *ABC* model as

$$QY = \frac{B(np - n_i^2)}{A(np - n_i^2)/p + B(np - n_i^2) + 2Cn(np - n_i^2)}$$
(1)

where *A*, *B* and *C* are the Shockley–Read–Hall (SRH), radiative bimolecular, and Auger recombination coefficients, respectively, and  $n_i$  and n/p are the intrinsic and total electron/ hole concentrations, respectively. The bP has a much higher

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**Figure 1.** (a) Schematic showing the device cross section. (b) Optical micrograph of a typical device with 80 nm BP, 8 nm  $MoS_2$ , 10 nm ITO, and 360 nm  $Al_2O_3$  layer. (c) Electroluminescence measured from the device shown in panel b as a function of the injection current density with a peak emission at 0.34 eV.

MWIR photoluminescence (PL) intensity than indium arsenide (InAs) multiple quantum well (MQW), confirming its prospects for photonic appplications.<sup>8</sup> Another advantage of bP is that its PL emission is linearly polarized.<sup>9</sup> Owing to its puckered honeycomb lattice, bP shows novel anisotropic optical, electronic, mechanical, thermal, and optical properties along the two orthogonal directions of armchair and zigzag.<sup>10,11</sup> Furthermore, the material shows high hole mobility, and has a direct and widely tunable thickness-dependent bandgap that ranges from 0.3 to 2 eV, a spectral region containing absorption lines of numerous gases.<sup>12,13</sup> This confirms the prospects of bP-based LEDs for applications involving selective sensing of gases.

The bP-LEDs investigated thus far are in the form of bP/ $MoS_2$  heterojunctions, which have intrinsic p- and n-type characteristics, respectively, and produce MWIR electro-luminescence.<sup>14,15</sup> It has also been shown that high output power can be achieved when the device is modified to include graphene electrodes to allow for the injection of a high current into the bP layer.<sup>16</sup> Even though these works have documented bP-LEDs with remarkable properties, there have not been extensive efforts to improve their external and wall-plug efficiencies. In this work, we demonstrate techniques to improve these metrics by addressing two key problems.

The first problem is that of limitations to the wall-plug efficiencies of the previously demonstrated bP-LEDs as a result of the high parasitic resistances of the materials. Even though MoS<sub>2</sub> forms a low Schottky barrier height with metal contacts (such as Au or Ni) for electron injection into bP, there is still considerable scope for reducing the overall resistance of the device. To shunt the lateral parasitic resistance of the MoS<sub>2</sub> layer, we employ a thin film of indium tin oxide (ITO). ITO has low resistivity because it is a n-type degenerate semiconductor.<sup>17</sup> We chose ITO rather than a metal as a result of its high optical transparency. Furthermore, mitigation of the parasitic resistance is critical for not only improving wall-plug efficiency but also extending the operating lifetime. This is because high parasitic resistances can lead to excessive device temperatures as a result of joule heating. This can contribute to melting/vaporizing/diffusing processes occurring in the device and accelerate void formation, which can ultimately lead to permanent device degradation and/or failure.<sup>18,19</sup>

Another issue with the bP-LED devices demonstrated thus far is that a large fraction of the generated photons is lost via either emission through the bottom side or total internal reflection, while only the extracted optical power determines the overall device performance. To improve the light extraction efficiency in conventional LEDs, various methods, including die shaping,<sup>20,21</sup> textured semiconductor surfaces,<sup>22,23</sup> contact

geometries,<sup>24,25</sup> anti-reflection optical coatings,<sup>26</sup> transparent contacts,<sup>27</sup> flip-chip packaging,<sup>28–30</sup> and resonant cavities,<sup>31–33</sup> have been employed. In particular, resonant cavities result in not only an enhanced light outcoupling but also a more directed far-field emission pattern, which makes resonant-cavity light-emitting diodes (RC-LEDs) desirable for optical communication systems.<sup>34</sup> Optical cavities have also been employed for enhancing the light absorption and, thus, photodetection performance of 2D materials.<sup>35,36</sup> In this study, an optical cavity consisting of gold and Al<sub>2</sub>O<sub>3</sub> films was formed under the light-emitting bP/MoS<sub>2</sub> heterojunction such that the emission couples to the resonant mode of the cavity, and therefore, enhances the emission efficiency of the bP-based LEDs.

A schematic of the cross section and an optical microscope image of the device are shown in panels a and b of Figure 1, respectively. The fabrication process is discussed in section S1 of the Supporting Information, and bP characterization with Raman spectroscopy is presented in section S2 of the Supporting Information. The bP flakes with thicknesses of  $40 \pm 5$  nm and MoS<sub>2</sub> flakes with thicknesses of  $8 \pm 2$  nm were used in all experiments. This results in an emission peak at ~0.34 eV ( $\lambda$  = 3.65  $\mu$ m) in our bP-LEDs with a full width at half maximum (fwhm) of ~0.7  $\mu$ m. Using bP flakes with appropriate thickness is important here, because its bandgap is strongly modulated by thickness. The bandgap of MoS<sub>2</sub> remains constant at 1.29 eV for bulk thicknesses.<sup>37</sup> Typical emission spectra measured at different injection current densities are shown in Figure 1c. These spectra were collected using a double-modulated lock-in detection technique, as described in section S3 of the Supporting Information. The electroluminescence intensity increases with a higher current injection density without any change in the peak energy. This confirms that the emission originates from the bP band edge recombination. The characterization of the polarized emission from the LED is shown in section S4 of the Supporting Information.

The Al<sub>2</sub>O<sub>3</sub>/Au optical cavity was designed using optical simulations. For an emitter with a low intrinsic quantum efficiency, the emission enhancement factor provided by an optical structure can be expressed as  $f_{\rm P}\eta_{\rm oc}$ , where  $f_{\rm P}$  is the Purcell factor (i.e., spontaneous emission rate enhancement provided by the optical medium) and  $\eta_{\rm oc}$  is the outcoupling efficiency (i.e., fraction of radiated photons that escape the optical structure and reach the upper half-space where they are collected).<sup>38</sup> The Al<sub>2</sub>O<sub>3</sub>/Au cavity can contribute to the emission enhancement through both of these factors. In the presence of the optical cavity, the portion of the emitted light traveling downward becomes reflected from the mirror and



**Figure 2.** (a) Schematic of the device cross section showing the constructive interference of emitted light as a result of the optical cavity. (b) Simulated vertical profile of the optical power for  $Al_2O_3$  thicknesses of 50, 360, and 500 nm for a fixed bP thickness of 40 nm. Optical simulations showing the (c) outcoupling efficiency, (d) Purcell factor, and (e) normalized emission enhancement factor variation for the device structure as a function of bP and  $Al_2O_3$  thickness for a MoS<sub>2</sub> thickness of 8 nm and an ITO thickness of 10 nm.



Figure 3. (a) I-V characteristic and extracted series resistance for devices with and without a 10 nm thick ITO film. (b) Output power density and (c) wall-plug efficiency as functions of the input power density for LEDs with and without a 10 nm thick ITO film.

interferes with the emitted light from bP. For the interference to be constructive, the spacer thickness should be  $\sim \lambda/(4n_s)$ , where  $n_s$  is the refractive index of the Al<sub>2</sub>O<sub>3</sub> spacer layer and  $\lambda$ is the wavelength of the emitted photons. Hence, the optical cavity with a proper spacer thickness enhances the outcoupling efficiency by redirecting the emitted light to the upper halfspace, where it can be collected. This is schematically illustrated in Figure 2a. Figure 2b shows the optical power variation along the depth of the device for Al<sub>2</sub>O<sub>3</sub> thicknesses of 50, 360, and 500 nm at  $\lambda$  = 3.65  $\mu$ m. The simulation details are discussed in section S5 of the Supporting Information. It can be seen that a spacer thickness of 360 nm leads to the highest light outcoupling and, thus, far-field optical power. Figure 2c plots the outcoupling efficiency as functions of Al<sub>2</sub>O<sub>3</sub> and bP thicknesses at fixed thicknesses of 10 nm ITO and 8 nm MoS<sub>2</sub>. For bP thicknesses smaller than 50 nm (on a 325 nm  $Al_2O_3/$ Au cavity), the outcoupling efficiency is enhanced by more

than ~50 times compared to the case without an  $Al_2O_3$  spacer. While the outcoupling efficiency of this structure reaches its maximum value of ~21% for bP thickness of 20 nm, the Purcell factor is not the highest in this range of bP and Al<sub>2</sub>O<sub>3</sub> thickness. As illustrated in Figure 2d, the Purcell factor is greater at an Al<sub>2</sub>O<sub>3</sub> thickness of ~100 nm and bP thickness of 100-150 nm. Figure 2e plots the normalized emission enhancement factor  $(f_{\rm P}\eta_{\rm oc})$  as functions of Al<sub>2</sub>O<sub>3</sub> and bP thicknesses. The bP films used in the experiments were 40 nm thick. Accordingly, an Al<sub>2</sub>O<sub>3</sub> thickness of 360 nm should be chosen to maximize the emission enhancement factor. The comparison of optical power for different bP thicknesses at the injection current density of 50 A cm<sup>-2</sup> on a 360 nm thick Al<sub>2</sub>O<sub>3</sub>/Au cavity is shown in section S6 of the Supporting Information. It should be noted that the optical behavior of ITO depends upon the material defect density and, thus, sputtering conditions.<sup>39,40</sup> Thus, the refractive index values of



**Figure 4.** (a) External quantum efficiency and (b) wall-plug efficiency as functions of the input current density plotted for 45 devices fabricated with constant  $MoS_2$ , bP, ITO, and  $Al_2O_3$  thicknesses (8, 40, 10, and 360 nm, respectively). Histograms of (c) external quantum efficiency and (d) wall-plug efficiency with Gaussian and Weibull fits, respectively, at the current density of 50 A cm<sup>-2</sup>.

ITO to be used in the simulations were determined for our specific deposition parameters, as described in section S7 of the Supporting Information.

To reduce the parasitic resistance, we employed a 10 nm thick ITO layer, which has a relatively low sheet resistance of 300  $\Omega$ /sq. The effect can be quantified by comparing current–voltage (*I-V*) characteristics of devices with and without ITO, as shown in Figure 3a. These devices have similar junction areas of 353  $\mu$ m<sup>2</sup> (with ITO) and 424  $\mu$ m<sup>2</sup> (without ITO). For large forward-bias voltages, where series resistance becomes important, the current per unit junction area for the device with ITO is higher by more than an order of magnitude compared to the device without ITO. The forward-bias series resistance is evaluated using the following method.<sup>34</sup> The diode is assumed to have a very high parallel resistance ( $R_p \rightarrow \infty$ ), yielding the following forward-bias *I–V* relation:

$$I = I_{\rm S} \, \exp\!\left(\frac{q(V - IR_{\rm S})}{n_{\rm ideal}kT}\right) \tag{2}$$

where  $I_S$  is the reverse-bias saturation current,  $R_S$  is the series resistance,  $n_{ideal}$  is the ideality factor, k is the Boltzmann constant, q is the electric charge on an electron, and T is the absolute temperature of the diode. Equation 2 leads us to

$$\frac{\mathrm{d}V}{\mathrm{d}I} = R_{\mathrm{S}} + \frac{n_{\mathrm{ideal}}kT}{q}\frac{1}{I} \tag{3}$$

The slope of the plot of IdV/dI versus I (section S8 of the Supporting Information) is then used to determine  $R_S$ , which is 0.0053 and 0.56  $\Omega$  cm<sup>2</sup> and for devices with and without ITO, respectively. Hence, an about 2 orders of magnitude reduction in series resistance is achieved.

The reduction in parasitic resistance via the ITO layer improves the maximum output power density and power efficiency of the device. The output optical power from the device was determined using the calibration method discussed in section S9 of the Supporting Information. Figure 3b shows that the device with a 10 nm thick ITO layer produces a maximum optical power of 2.2 W/cm<sup>2</sup>, which is more than 5 times higher than that for the device without ITO, i.e., 0.4 W/cm<sup>2</sup>. Despite having a slightly lower photon extraction efficiency, the device with ITO shows higher brightness per unit area. This can be attributed to the reduction in series resistance achieved via the ITO layer, which improves the voltage drop across the device.

The LED with low parasitic resistance outperforms the device without ITO in terms of power efficiency as well, as shown in Figure 3c. This is also called wall-plug efficiency  $(\eta_{power})$  and is the ratio of the total detected optical power (P) to the total input electrical power injected into the device

$$\eta_{\text{power}} = \frac{\text{detected optical power}}{\text{input electrical power}} = \frac{P}{IV}$$
(4)

The device with ITO achieves a wall-plug efficiency of 0.3% at an input power density of 418 W/cm<sup>2</sup>, while for the device without ITO, the wall-plug efficiency is 0.07% at a (similar) input power density of 435 W/cm<sup>2</sup>.

The output power density increases sub-linearly with input power density according to the "efficiency-droop" effect; i.e., external quantum efficiency ( $\eta_{EQE}$ ) is reduced as a result of Auger recombination at higher carrier densities.<sup>41,42</sup>  $\eta_{EQE}$  is defined as the ratio between the number of detected photons and the number of electrons injected into the device

$$\eta_{\rm EQE} = \frac{\text{number of detected photons}}{\text{number of injected electrons}} = \frac{P/(hc/\lambda)}{I/q}$$
(5)

where *h* is Planck's constant, *c* is the speed of light, and  $\lambda$  is the wavelength of the emitted photons. For devices with and without a 10 nm ITO layer, the output power density saturates at input power densities of ~3000 and 1000 W/cm<sup>2</sup>, respectively, and it starts drooping with increasing input power. It is anticipated that the junction temperature plays a significant role here, because Auger recombination coefficients increase exponentially with increasing temperature<sup>43</sup> and no



Figure 5. Drift of optical power density measured for a duration of 10 h at a modulation frequency of 1 kHz, injection current density of 20.4 A/  $cm^2$ , and output power of ~0.2 W/cm<sup>2</sup>. The dotted line shows the mean of the signal.

Table 1. Benchmark Comparison of the bP-LED Demonstrated in This Work with the State-of-the-Art 1	MWIR Light Emitters
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material system	technology	wavelength ( $\mu$ m)	maximum optical power density $(W/cm^2)$	peak $\eta_{\mathrm{EQE}}$ (%)	reference
bP-LED	LED	3.65	2.17	4.43	this work
InAs	LED	3.3	3.14	0.44	44
CdHgTe	LED	3.2	0.97	0.02	45
InAsSb	LED	4.3	0.32	0.35	46
GalnAsSb	LED	2.34	0.4	2.5	47
InAs/GalnSb/InAs	interband cascade	3.8	2.4	0.65	48
InAs/GalnSb/InAs	interband cascade	3.8	2	3.1	49
InGaAs/AllnAs	quantum cascade	3.56	857	95.7	50
InGaAs/AllnAs	quantum cascade	3.5	139	10	51
Hamamatsu L13454	LED	3.9	0.6	0.9	52
Boston Electronics LED38TO8TEC	LED	3.8	0.2	0.1	53
Thorlabs LED3800W	LED	3.8	1.5	0.2	54

temperature control mechanism (e.g., heat sinking or thermoelectric cooling) is implemented here. This results in further deterioration of external quantum efficiency (and, consequently, the output power) at higher input powers. Therefore, a possible rationale for the delayed onset of droop in devices with ITO is the lower junction temperature compared to devices without ITO. The dramatic decrease in the wall-plug efficiency with an increasing input power also originates from the reduced external quantum efficiency. While the ITO layer reduces the parasitic resistance of  $MoS_2$ , it does not affect the parasitic resistance of bP and the contact resistance.

Next, we performed a statistical study on 45 devices to determine the device-to-device variations. The results are presented in Figure 4. The "efficiency-droop" effect can be clearly observed in Figure 4a, with the peak external quantum efficiency of the champion device being 4.43% at the input current density of 14 A cm<sup>-2</sup> and reducing to 0.90% at the current density of 638 A cm<sup>-2</sup>. The corresponding output power densities at these current densities are 0.22 and 2.04 W/ cm<sup>2</sup>, respectively. The maximum output power density recorded from this device with an area of 353  $\mu$ m<sup>2</sup> is 2.17  $W/cm^2$  (i.e., output power = 7.68  $\mu W$ ) at an injected carrier density of  $6.2 \times 10^{21}$  cm<sup>-2</sup>. The device with the lowest peak external quantum efficiency of 0.49% at the current density of 15 A cm<sup>-2</sup> exhibits a wall-plug efficiency of 0.15%, as shown in Figure 4b. Its maximum output power is 2.21  $\mu$ W, achieved at an input current density of 304 A cm<sup>-2</sup>. The highest wall-plug efficiency among the 45 devices (i.e., for the champion device) is 1.78%, achieved at a current density of 14 A cm<sup>-2</sup>. This device exhibits a power efficiency of 0.035% at the highest injected current density of 638 A cm<sup>-2</sup>.

Histograms of the external quantum efficiency and wall-plug efficiency of the 45 devices are presented in panels c and d of

Figure 4, respectively. For fair comparison, the performance of the devices is evaluated at the same injection current density (of 50 A cm<sup>-2</sup>), which is done through interpolation. The histogram of the external quantum efficiency follows a normal distribution with a mean of ~1.5%, as shown in Figure 4c. The minimum and maximum quantum efficiencies are 0.45 and 3.33%, respectively. The histogram of the wall-plug efficiency, as shown in Figure 4d, follows a Weibull distribution with a shape value of less than 3 (right-skewed) and a peak at ~0.17%. The minimum and maximum power efficiencies are 0.05 and 0.70%, respectively. This variability is attributed to the minor differences in the thicknesses of the layers (which modifies the extraction efficiency) and air exposure of bP during fabrication.

Figure 5 presents the drift characteristics of a test device. It shows a maximum variation of less than 2% from the mean signal in the measurement period of more than 10 h, indicating high stability. Finally, the performance of our bP-LEDs is benchmarked against the state-of-the-art MWIR light sources, such as LEDs, interband, and quantum cascade lasers, having emission wavelengths in the range of 2–4.3  $\mu$ m. As shown in Table 1, our bP-LED outperforms the LEDs based on conventional material systems in terms of maximum optical power density (W/cm<sup>2</sup>) and peak  $\eta_{EQE}$  (%) at room temperature. Although lagging behind the highly efficient quantum cascade laser technology, our device exhibits higher external quantum efficiency than commercially available LEDs and shows an overall comparable performance to interband cascade lasers.

In conclusion, we have demonstrated a bright and efficient electroluminescent MWIR light emitter based on bP. This is accomplished by leveraging the low Auger recombination rate in bP, an  $Al_2O_3/Au$  optical cavity to enhance the photon

extraction, and a thin transparent and conductive ITO layer to reduce the high n-side parasitic resistances. We suggest several topics for future work. Investigation of diode failure mechanisms would help to improve the injectable power and, thus, the maximum optical power. Strategies to encapsulate air-sensitive bP with oxides, 2D materials, and organics should be investigated and may further enhance the long-term stability of the device.55,56 Studies on tuning the bP bandgap via strain engineering,<sup>7,57</sup> designing optical coupling structures, such as nano-antennas, for light emission enhancement,<sup>38</sup> and designing waveguides for integration with silicon photonic platforms<sup>16</sup> would help advance bP-LEDs for realworld applications. The device performance may also be improved via better alternative electron contacts to MoS<sub>2</sub>, electrical/chemical doping,<sup>58</sup> double heterostructure,<sup>59</sup> and other high extraction efficiency designs.<sup>60</sup> The future works on these topics can be rewarding as a result of the potential of bP-LEDs to serve as the next-generation MWIR sources.

## ASSOCIATED CONTENT

#### **Supporting Information**

The Supporting Information is available free of charge at https://pubs.acs.org/doi/10.1021/acs.nanolett.1c04557.

Fabrication of bP-LED (section S1), Raman spectroscopy (section S2), device electrical and optical measurements (section S3), polarized electroluminescence (section S4), optical simulation setup (section S5), effect of bP thickness on the optical power (section S6), ITO refractive index estimation (section S7), series resistance calculation (section S8), and calibration of the output power (section S9) (PDF)

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Hyungjin Kim, Shiekh Zia Uddin, and Der-Hsien Lien contributed to the calibration process. Niharika Gupta, Nima Sefidmooye Azar, and Shiekh Zia Uddin performed the optical simulations. Niharika Gupta carried out the fabrication and measurements. All authors discussed the results and wrote the paper.

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#### Notes

The authors declare no competing financial interest.

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